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FIG.1

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START

STORE WAFER ID AND LAYER NAME FROM REVIEW APPARATUS 52 TO MAIN STORAGE DEVICE 62 VIA LOCAL AREA NETWORK 54 AND NETWORK INTERFACE 65

-101

SEARCH DEFECT MAP DATA FROM INSPECTION DATA DATABASE WITHIN AUXILIARY STORAGE DEVICE 63 BASED ON WAFER ID AND LAYER NAME WITHIN MAIN STORAGE DEVICE 62 AND THEN STORE THE DEFECT MAP DATA IN MAIN STORAGE DEVICE 62

-102

READ FAILURE PROBABILITY DATA WITHIN AUXILIARY STORAGE DEVICE 63 BASED ON WAFER ID AND LAYER NAME WITHIN MAIN STORAGE DEVICE 62 AND THEN STORE FAILURE PROBABILITY DATA IN MAIN STORAGE DEVICE 62

-103

CALCULATE DEFECT COUNT "N" OF DEFECT MAP DATA WITHIN MAIN STORAGE DEVICE 62

105

REPEAT FROM DEFECT #1 TO #N

COMPARE X-AND Y-COORDINATES OF EACH DEFECT MAP DATA WITH BLOCK COORDINATES OF FAILURE PROBABILITY DATA, THEN JUDGE BLOCK NAME AND WHETHER BLOCK EDGE OR NOT FOR EACH DEFECT, AND THEN STORE JUDGEMENT RESULT IN MAIN STORAGE DEVICE 62

106

CALCULATE FAILURE PROBABILITY BASED ON DEFECT DIAMETER OF EACH DEFECT MAP DATA AND FAILURE PROBABILITY DATA AND THEN STORE THE FAILURE PROBABILITY IN MAIN STORAGE DEVICE 62

107

READ BLOCK NAME, DATA AS TO WHETHER BLOCK EDGE OR NOT, AND FAILURE PROBABILITY WITHIN MAIN STORAGE DEVICE 62, AND THEN UPDATE DEFECT MAP DATA TO FAILURE PROBABILITY ADDED DEFECT MAP DATA

108

109

COMPLETE REPEATING AFTER EXECUTION OF DEFECT #N

READ REVIEW CONDITION FILE WITHIN AUXILIARY STORAGE DEVICE 63 BASED ON WAFER ID AND LAYER NAME AND THEN STORE THE CONDITION IN MAIN STORAGE DEVICE 62

110

SORT DEFECT MAP DATA WITHIN MAIN STORAGE DEVICE 62 SO THAT DEFECT WITH HIGHEST FAILURE PROBABILITY COMES FIRST AND THEN STORE SORTED DEFECT MAP DATA IN MAIN STORAGE DEVICE 62

-111

CLASSIFY DEFECT MAP DATA INTO DEFECTS TO BE REVIEWED AND THOSE NOT TO BE REVIEWED USING REVIEW CONDITION WITHIN MAIN STORAGE DEVICE 62, THEN SELECT DEFECTS TO BE REVIEWED, AND THEN STORE RESULTS IN MAIN STORAGE DEVICE 62

-112

TRANSFER SELECTED RESULTS WITHIN MAIN STORAGE DEVICE 62 TOWARD REVIEW APPARATUS 52 VIA NETWORK INTERFACE 65 AND LOCAL AREA NETWORK 54

-113

END

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FIG.2

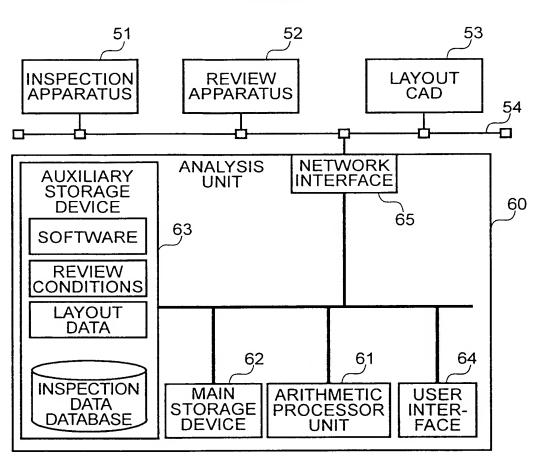


FIG.3

_							-
	NO.,	CHIP COLUMN,	CHIP ROW,	Χ,	Y,	DEFECT DIAMETER	
۱	1,	1,	1,	73,	67,	2.4	21
	2,	5,	1,	25,	89,	0.3	ľ
١	2, 3,	4,	2,	47,	69,	1.5	
١	4,	5,	3,	80,	82,	1.0	ł
١	5,	6,	5,	52,	78,	1.2	
1	6,	3,	5,	71,	32,	0.2	
1	7,	3,	7,	87,	90,	0.7	
١	8,	2,	6,	77,	38,		
١	9,	Ο,	4,	83,	45,		
١	10,	2,	3,	49,	9,	1.9	J
L						<i></i>	

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FIG.4

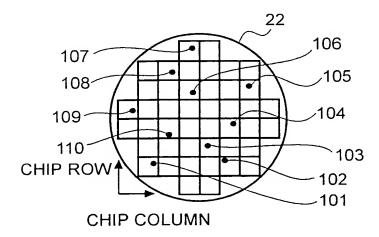
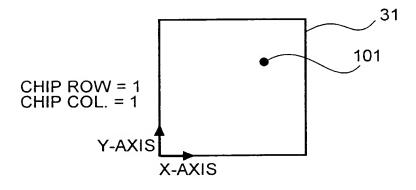


FIG.5



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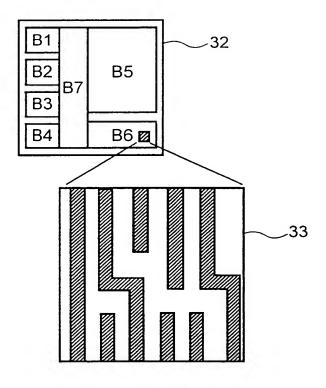
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FIG.6



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FIG.7

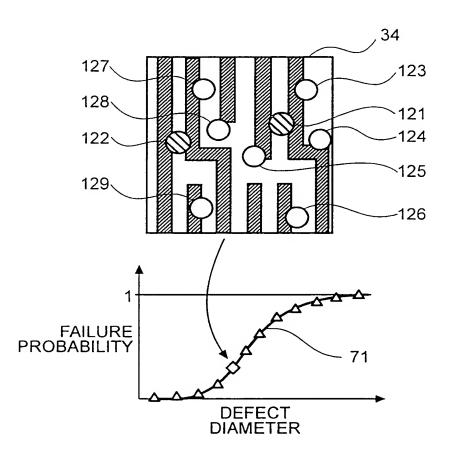
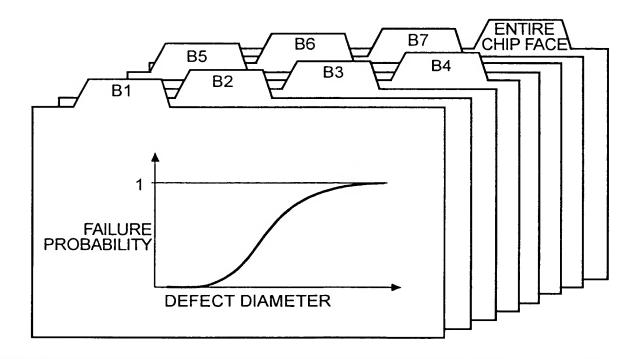


FIG.8



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FIG.9

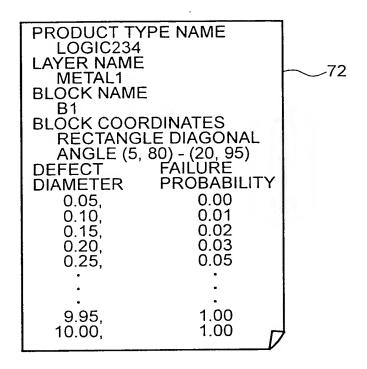
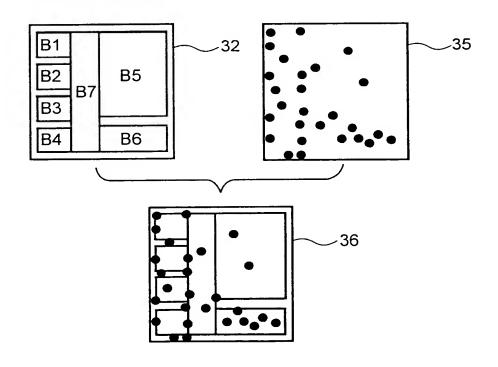


FIG.10



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23

NO.,	CHIP COL.,	CHIP ROW,	Χ,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
11.	1,	1,	73,	67,	2.4,	B5,	no,	0.83
2,	5,	1,	25,	89,	0.3,	B1,	no,	0.07
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
6.	3,	5,	71,	32,	0.2,	B6,	yes,	0.05
7.	3,	7,	87,	90,	0.7,	B5,	no,	0.35
8.	2,	6,	77,	38,	0.3,	B6,	no,	0.07
9.	0.	4,	83,	45,	0.8,	B5,	no,	0.28
10,	2,	3,	49,	9,	1.9,	B7,	no,	0.06

FIG.12

24

								
NO.,	CHIP COL.,	CHIP ROW,	Χ,	Υ,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
5.	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7.	87,	90,	0.7,	B5,	no,	0.35
9,	O,	4,	83,	45,	0.8,	B5,	no,	0.28
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
8,	2,	6,	77,	38,	0.3,	B6,	no,	0.07
2,	5,	1.	25,	89,	0.3,	B1,	no,	0.07
10.	2,	3,	49,	9,	1.9,	B7,	no,	0.06
6,	3,	5,	71,	32,	0.2,	B6,	yes,	0.05
1								1/

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FIG.13

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	CHIP	CHIP					BLOCK	
NO.,	COL.,	ROW,	Χ,	Y,	SIZE,	BLOCK,	EDGE,	PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
4.	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7.	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9.	0.	4,	83.	45,	0.8,	B5,	no,	0.28
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
1 '	•	•	•	•	·		•	

FIG.14

CHIP CHIP NO., COL., ROW, 3, 4, 2, 8, 2, 6, 2, 5, 1, 10, 2, 3, 6, 3, 5,	X, Y, 47, 69, 77, 38, 25, 89, 49, 9, 71, 32,	1.5, B2, 0.3, B6, 0.3, B1, 1.9, B7,	BLOCK EDGE, no, no, no, yes,	FAILURE PROBABILITY 0.26 0.07 0.07 0.06 0.05

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NO	CHIP ., COL.,	CHIP ROW,	Χ,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28

FIG.16

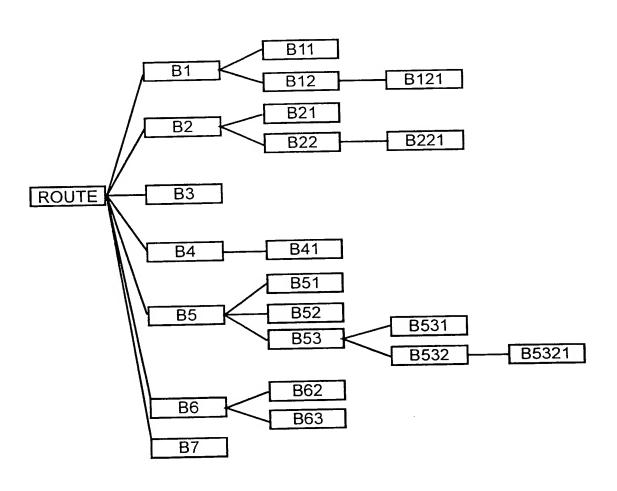
PRODUCT TYPE NAME LOGIC234 LAYER NAME METAL1 MAXIMUM DEFECT NUMBER 20 **OBJECT FAILURE PROBABILITY** 0.30 OR GREATER **EXCLUDED B5 BLOCK EDGES B1, B2**

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FIG.17



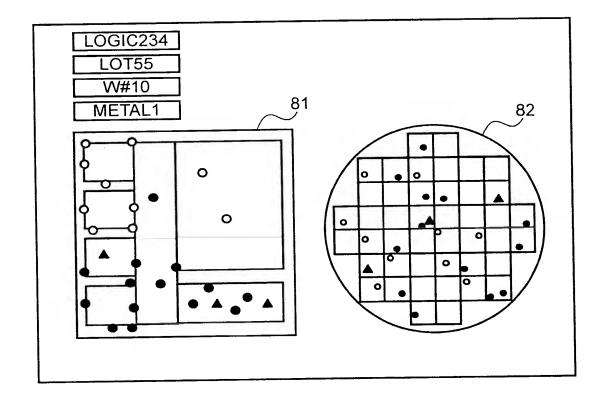
Title:

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FIG.18

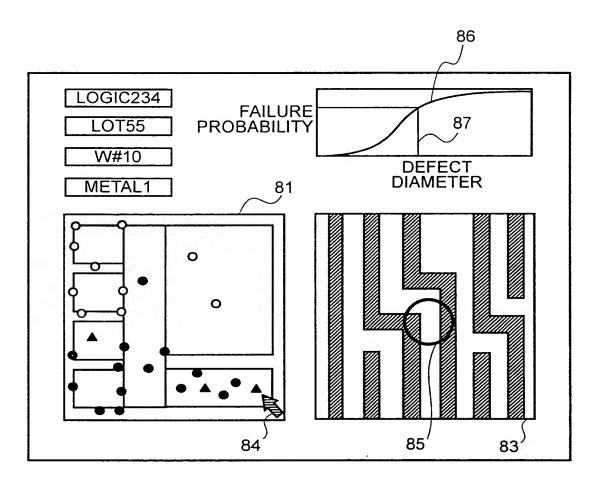


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